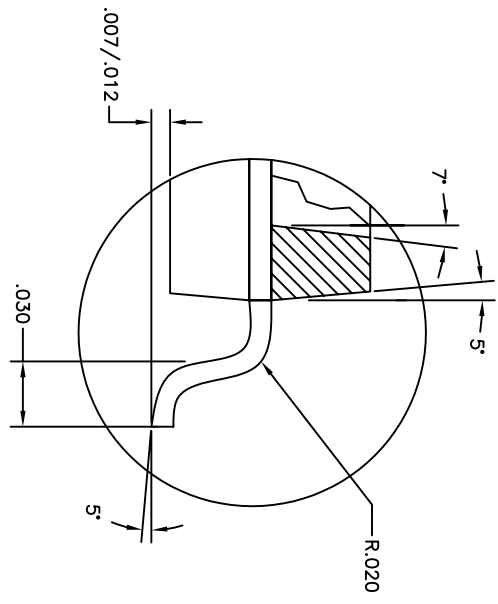
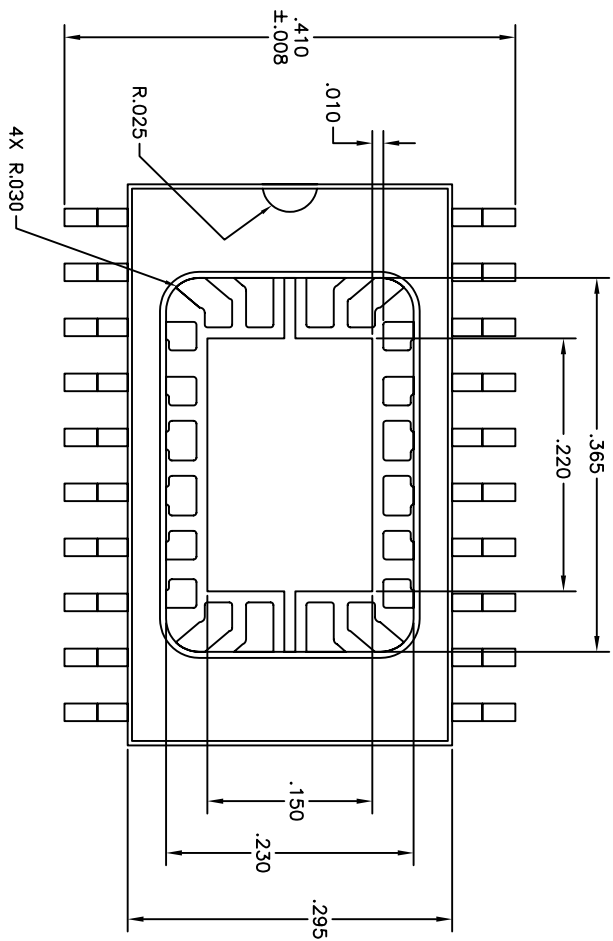


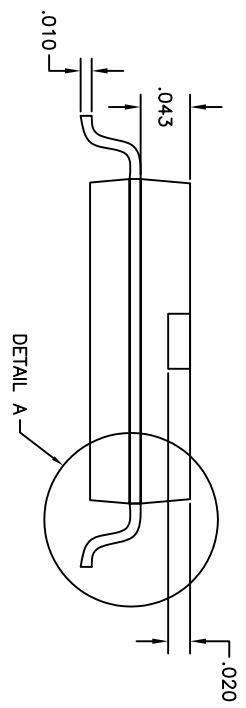
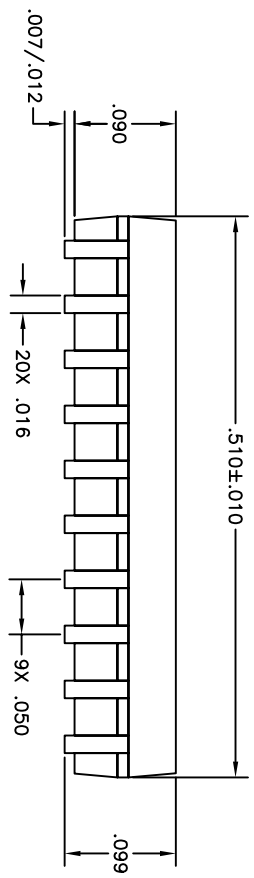
2

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REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D. BENNANO
10192	03/24/05	INCORPORATE CHANGES PER ECON	



DETAIL A
SCALE: 2/1



DETAIL A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEADFRAME: COPPER, OLIN 194.
 3. LEAD FINISH: FULL Au PLATE.
 4. DIE PAD: .220" x .150".



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± .0001 X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	R. PEREZ	DATE	03/24/05
APP BY	P. FLASKERUD	DATE	03/25/05
CUSTOMER	---		

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Open-Pak™ Technologies
www.open-pak.com
 568 E. WEDDELL DRIVE, SUITE 5
 SUNNYVALE, CALIFORNIA 94089
 PHONE: (408) 400-9002 FAX: (408) 400-9006

20 LEAD 300 mil
 SOIC Open-Pak

SIZE	PART NO.	REV
A	SOIC300-20-OP-01	2

SCALE NONE FILE SOIC300-20-OP-01-1-R2.DWG SHEET 1 OF 1

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